As a below named Inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name;

123 Park Avenue 3, Science-Based Industrial Park, Hsin-Chu, Taiwan, Republic of China Post Office Address

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled On-Chip Disign-For-Testing Structure For CMOS APS Image Sensor the specification of which (check one 0 7 2001 X is attached hereto. was filed on Application Serial No. and was amended on I hereby state that I have reviewed and understand the contents of the above Identified specification including the claims, as (if applicable) I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a). I hereby claim foreign priority benefits under Title 35, United States Code §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed: Priority Claimed: (Number) (Country) (Day/Month/Year Filed) (Number) (Country) (Day/Month/Year Filed) I hereby claim the benefit under Title 35, United States Code §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as national or PCT international filing date of this application: (Application Serial No.) (Filing Date) (Status) (patented, pending, abandoned) I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon. POWER OF ATTORNEY: As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith. (list name & registration no.) (Reg. No. 19,572), STEPHEN B. ACKERMAN (Reg. No. 37,761) Send Correspondence to: 20 MCINTOSH DRIVE, POUGHKEEPSIE; NEW YORK 12603 Direct telephone Calls to: (name & telephone number) GEORGE 0. SAILE NEW YORK 914 452 5863 <u>SUNETRA K. MENDIS</u> Full name of sole or first inventor Date Inventor's signature 700/ 158 Tennyson Avenue, Palo Alto, CA 94301 SRI LANKA Citizenship

## ATTORNEY FOR PATEN DECLARATION AND E As a below named Inventor, I hereby declare that: LOCKET NO. VISA-54 SEP 0 7 2001

My residence, post office address and citizenship are as stated below next to my name;

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled On-Chip Disign-For-Testing Structure For CMOS APS Image Sensor

the specification of which (check one)		
X is attached hereto.		
was filed onApplication Serial No.		
Application Serial Noand was amended on		
and was amended on		
I hereby state that I have reviewed and unde amended by any amendment referred to abo	cable) erstand the contents of the	above Identified specification including the claims, as
I acknowledge the duty to disclose informat 37, Code of Federal Regulations, §1, 56(a)	ion which is material to the	e examination of this application in accordance with Title
I hereby claim foreign priority benefits under inventor's certificate listed below and have a filing date before that of the application on Prior Foreign Application(s)	r Title 35, United States C ilso identified below any f which priority is claimed	Code §119 of any foreign application(s) for patent or or or or patent or inventor's certificate having
(Number)		Priority Claimed:
	(Country)	· 5
(Number)	(Country)	(Day/Month/Year Filed)  my United States application(s) listed below and, insofar losed in the prior United States application in the manner.
national or PCT international filing date of thi	ons, §1.56(a) which occur s application:	acknowledge the duty to disclose material information as red between the filing date of the prior application and the
I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.		
application and transact all business in the Pate	or, I hereby appoint the form	ollowing attorney(s) and/or agent(s) to prosecute this connected therewith. (list name & registration no.)  CKERMAN (Reg. No. 37,761)
Send Correspondence to: 20 MCINTOSH DRI Direct telephone Calls to: (name & telephone num  TZI-HSIUNG SHU  Full name of sole or first inventor  Inventor's panagare  1150 Lockhaven Way, San Jose, CA 9512  Fesidence	IVE, POUGHKEEPSIE; ber) GEORGE 0. SAII	
Citizenship  123 Park Avenue 3. Science-Based Industrial Park, Hsin-Chu, Taiwan, Republic of China  Post Office Address		